

MILITARY SPECIFICATION
MICROCIRCUITS, DIGITAL, CMOS, OR GATES,
MONOLITHIC SILICON, POSITIVE LOGIC

Reactivated after 17 Feb. 2004 and may be used for new and existing designs and acquisitions.

This specification is approved for use by all Departments
and Agencies of the Department of Defense.

The requirements for acquiring the product herein shall consist of this specification sheet and MIL-PRF 38535

1. SCOPE

1.1 Scope. This specification covers the detail requirements for monolithic silicon, CMOS, logic microcircuits. Two product assurance classes and a choice of case outlines, lead finishes, and radiation hardness assurance (RHA) are provided and are reflected in the complete Part or Identifying Number (PIN). For this product, the requirements of MIL-M-38510 have been superseded by MIL-PRF-38535 (see 6.3).

1.2 Part or identifying number (PIN). The PIN is in accordance with MIL-PRF-38535 and as specified herein.

1.2.1 Device types. The device types are as follows:

<u>Device type</u>	<u>Circuit</u>
01	Quad 2-input OR gate
02	Dual 4-input OR gate
03	Triple 3-input OR gate

1.2.2 Device class. The device class is the product assurance level as defined in MIL-PRF-38535.

1.2.3 Case outlines. The case outlines are as designated in MIL-STD-1835 and as follows:

<u>Outline letter</u>	<u>Descriptive designator</u>	<u>Terminals</u>	<u>Package style</u>
A	GDFF5-F14 or CDFP6-F14	14	Flat pack
C	GDIP1-T14 or CDIP2-T14	14	Dual-in-line
D	GDFF1-F14 or CDFP2-F14	14	Flat pack
T	CDFP3-F14	14	Flat pack
X <u>1/</u> <u>2/</u>	GDFF5-F14 or CDFP6-F14	14	Flat pack, except A dimension equals 0.1" (2.54 mm) max
Y <u>1/</u> <u>2/</u>	GDFF1-F14 or CDFP2-F14	14	Flat pack, except A dimension equals 0.1" (2.54 mm) max

1/ As an exception to 3.5.6.2.3 of MIL-M-38510 superseded by MIL-PRF-38535, appendix A, for case outlines X and Y only, the leads of bottom brazed ceramic packages (i.e., configuration 2 of case outlines F-1 or F-2) may have electrodes nickel undercoating which is 50 to 200 microinches (1.27 to 5.08 μ m) thick provided the lead finish is hot solder dip (i.e., finish letter A) and provided that, after any lead forming, an additional hot solder dip coating is applied which extends from the outer tip of the lead to no more than 0.015 inch (0.38 mm) from the edge.

2/ For bottom or side brazed packages, case outlines X and Y only, the S₁ dimension may go to .000 inch (.00 mm) minimum.

Comments, suggestions, or questions on this document should be addressed to: Commander, Defense Supply Center Columbus, ATTN: DSCC-VAC, 3990 East Broad St., Columbus, OH 43216-5000, or email CMOS@dsc.dla.mil. Since contact information can change, you may want to verify the currency of this address information using the ASSIST Online database at www.dodssp.daps.mil .

MIL-M-38510/171C

1.3 Absolute maximum ratings.

Supply voltage range ($V_{DD} - V_{SS}$).....	-0.5 V dc to +18.0 V dc
Input current (each input)	± 10 mA
Input voltage range	$(V_{SS} - 0.5) \leq V_I \leq (V_{DD} + 0.5)$
Storage temperature range (T_{STG}).....	-65° to +175°C
Maximum power dissipation (P_D)	200 mW
Lead temperature (soldering, 10 seconds)	+300°C
Thermal resistance, junction to case (Θ_{JC})	See MIL-STD-1835
Junction temperature (T_J)	175°C

1.4 Recommended operating conditions.

Supply voltage range ($V_{DD} - V_{SS}$).....	4.5 V dc to 15.0 V dc
Input low voltage range (V_{IL})	$V_{OL} = 10\% V_{DD}$, $V_{OH} = 90\% V_{DD}$ 0.0 V to 1.5 V dc @ $V_{DD} = 5.0$ V dc 0.0 V to 2.0 V dc @ $V_{DD} = 10.0$ V dc 0.0 V to 4.0 V dc @ $V_{DD} = 15.0$ V dc
Input high voltage range (V_{IH}).....	$V_{OL} = 10\% V_{DD}$, $V_{OH} = 90\% V_{DD}$ 3.5 V to 5.0 V dc @ $V_{DD} = 5.0$ V dc 8.0 V to 10.0 V dc @ $V_{DD} = 10.0$ V dc 11 V to 15.0 V dc @ $V_{DD} = 15.0$ V dc
Operating temperature range (T_A)	-55°C to +125°C

2. APPLICABLE DOCUMENTS

2.1 General. The documents listed in this section are specified in sections 3, 4, or 5 of this specification. This section does not include documents cited in other sections of this specification or recommended for additional information or as examples. While every effort has been made to ensure the completeness of this list, document users are cautioned that they must meet all specified requirements of documents cited in sections 3, 4, or 5 of this specification, whether or not they are listed.

2.2 Government documents.

2.2.1 Specifications and Standards. The following specifications and standards form a part of this specification to the extent specified herein. Unless otherwise specified, the issues of these documents are those cited in the solicitation or contract.

DEPARTMENT OF DEFENSE SPECIFICATION

MIL-PRF-38535 - Integrated Circuits (Microcircuits) Manufacturing, General Specification for.

DEPARTMENT OF DEFENSE STANDARDS

MIL-STD-883 - Test Method Standard Microcircuits.
MIL-STD-1835 - Interface Standard Electronic Component Case Outlines.

(Copies of these documents are available online at <http://assist.daps.dla.mil/quicksearch/> or www.dodssp.daps.mil or from the Standardization Document Order Desk, 700 Robbins Avenue, Building 4D, Philadelphia, PA 19111-5094.)

2.3 Order of precedence. In the event of a conflict between the text of this document and the references cited herein, the text of this document takes precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained.

3. REQUIREMENTS

3.1 Qualification. Microcircuits furnished under this specification shall be products that are manufactured by a manufacturer authorized by the qualifying activity for listing on the applicable qualified manufacturers list before contract award (see 4.3 and 6.4).

3.2 Item requirements. The individual item requirements shall be in accordance with MIL-PRF-38535 and as specified herein or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein.

3.3 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-PRF-38535 and herein. Although eutectic die bonding is preferred, epoxy die bonding may be performed. However the resin used shall be Dupont 5504 Conductive Silver Paste, or equivalent, which is cured at $200^{\circ}\text{C} \pm 10^{\circ}\text{C}$. for a minimum of 2 hours. The use of equivalency epoxies or cure cycles shall be approved by the qualifying activity. Equivalency shall be demonstrated in data submitted to the qualifying activity for verification.

3.3.1 Logic diagrams and terminal connections. The logic diagrams and terminal connections shall be as specified on figure 1.

3.3.2 Truth tables and logic equations. The truth tables and logic equations shall be as specified on figure 2.

3.3.3 Switching time test circuit and waveforms. The switching time test circuit and waveforms shall be as specified on figure 3.

3.3.4 Schematic circuits. The schematic circuits shall be maintained by the manufacturer and made available to the qualifying activity or preparing activity upon request.

3.3.5 Case outlines. The case outlines shall be as specified in 1.2.3.

3.4 Lead material and finish. The lead material and finish shall be in accordance with MIL-PRF-38535 (see 6.6).

3.5 Electrical performance characteristics. Unless otherwise specified, the electrical performance characteristics are as specified in table I, and apply over the full recommended ambient operating temperature range.

3.6 Electrical test requirements. The electrical test requirements for each device class shall be the subgroups specified in table II. The electrical tests for each subgroup are described in table III.

3.7 Marking. Marking shall be in accordance with MIL-PRF-38535.

3.7.1 Radiation hardness assurance identifier. The radiation hardness assurance identifier shall be in accordance with MIL-PRF-38535 and 4.5.4 herein.

3.8 Microcircuit group assignment. The devices covered by this specification shall be in microcircuit group number 36 (see MIL-PRF-38535, appendix A).

TABLE I. Electrical performance characteristics.

Test	Symbol	Conditions $V_{SS} = 0\text{ V}$ $-55^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ Unless otherwise specified	Device type	Limits		Unit
				Min	Max	
Positive clamping input to V_{DD}	$V_{IC}(\text{POS})$	$T_A = +25^{\circ}\text{C}$, $V_{DD} = \text{GND}$ $V_{SS} = \text{Open}$, Output = Open $I_{IN} = 1\text{ mA}$	All		1.5	V dc
Negative clamping input to V_{SS}	$V_{IC}(\text{NEG})$	$T_A = +25^{\circ}\text{C}$, $V_{DD} = \text{GND}$ $V_{SS} = \text{GND}$, Output = Open $I_{IN} = -1\text{ mA}$	All		-6.0	V dc
Quiescent supply current	I_{SS} or I_{DD}	$V_{DD} = 18\text{ V dc}$ $V_{IN} = V_{SS}$ or V_{DD} All input combinations	All		-750	nA
High level output voltage	V_{OH1}	$V_{DD} = 15\text{ V dc}$ Any one input = V_{DD} All other inputs = V_{SS} $ I_O \leq 1\mu\text{A}$	All	14.95		V dc
Low level output voltage	V_{OL1}	$V_{DD} = 15\text{ V dc}$ $V_{IN} = V_{SS}$ $ I_O \leq 1\mu\text{A}$	All		0.05	V dc
Input high voltage	V_{IH1}	$V_{DD} = 5\text{ V dc}$ Any one input = 3.5 V dc All other inputs = V_{SS} $V_O = 4.5\text{ V}$ $ I_O \leq 1\mu\text{A}$	All	3.5		V dc
	V_{IH2}	$V_{DD} = 10\text{ V dc}$ Any one input = 7.0 V dc All other inputs = V_{SS} $V_O = 9.0\text{ V}$ $ I_O \leq 1\mu\text{A}$	All	7.0		V dc
	V_{IH3}	$V_{DD} = 15\text{ V dc}$ Any one input = 11.0 V dc All other inputs = V_{SS} $V_O = 13.5\text{ V}$ $ I_O \leq 1\mu\text{A}$	All	11.0		V dc
Input low voltage	V_{IL1}	$V_{DD} = 5\text{ V dc}$ Any one input = 1.5 V dc All other inputs = V_{SS} $V_O = 0.5\text{ V dc}$ $ I_O \leq 1\mu\text{A}$	All		1.5	V dc
	V_{IL2}	$V_{DD} = 10\text{ V dc}$ Any one input = 3.0 V dc All other inputs = V_{SS} $V_O = 1.0\text{ V dc}$ $ I_O \leq 1\mu\text{A}$	All		3.0	V dc
	V_{IL3}	$V_{DD} = 15\text{ V dc}$ Any one input = 4.0 V dc All other inputs = V_{SS} $V_O = 1.5\text{ V dc}$ $ I_O \leq 1\mu\text{A}$	All		4.0	V dc

TABLE I. Electrical performance characteristics – Continued.

Test	Symbol	Conditions $V_{SS} = 0\text{ V}$ $-55^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ Unless otherwise specified	Device type	Limits		Unit
				Min	Max	
Output high (source) current	I_{OH1}	$V_{DD} = 5\text{ V dc}$ Any one input = V_{DD} All other inputs = V_{SS} $V_{OH} = 4.6\text{ V dc}$	All	-0.36		mA dc
	I_{OH2}	$V_{DD} = 15\text{ V dc}$ Any one input = V_{DD} All other inputs = V_{SS} $V_{OH} = 13.5\text{ V dc}$	All	-2.4		mA dc
Output low (sink) current	I_{OL1}	$V_{DD} = 5\text{ V dc}$ $V_{IN} = V_{SS}$ $V_{OL} = 0.4\text{ V dc}$	All	0.36		mA dc
	I_{OL2}	$V_{DD} = 15\text{ V dc}$ $V_{IN} = V_{SS}$ $V_{OL} = 1.5\text{ V dc}$	All	2.4		mA dc
Input leakage <u>1</u> / current, high	I_{IH}	$V_{DD} = 18\text{ V dc}$ Measure inputs sequentially Connect all unused inputs to V_{SS}	01, 03		100	nA
			02		45	
Input leakage <u>1</u> / current, low	I_{IL}	$V_{DD} = 18\text{ V dc}$ Measure inputs sequentially Connect all unused inputs to V_{DD}	01, 03		-100	nA
			02		-45	
Input capacitance	C_i	$V_{DD} = 0\text{ V dc}$, $f = 1\text{ MHz}$, $T_A = 25^{\circ}\text{C}$	All		7.5	pF
Propagation delay times, high to low level	t_{PHL}	$V_{DD} = 5\text{ V dc}$, $C_L = 50\text{ pF}$ $R_L = 200\text{ k}\Omega$ (See figure 3)	All	13	350	ns
		$V_{DD} = 10\text{ V dc}$, $C_L = 50\text{ pF}$ $R_L = 200\text{ k}\Omega$ $T_A = +25^{\circ}\text{C}$, (See figure 3)	All	6	120	ns
Propagation delay times, low to high level	t_{PLH}	$V_{DD} = 5\text{ V dc}$, $C_L = 50\text{ pF}$ $R_L = 200\text{ k}\Omega$ (See figure 3)	All	13	350	ns
		$V_{DD} = 10\text{ V dc}$, $C_L = 50\text{ pF}$ $R_L = 200\text{ k}\Omega$ $T_A = +25^{\circ}\text{C}$, (See figure 3)	All	6	120	ns
Transition times, high to low level	t_{THL}	$V_{DD} = 5\text{ V dc}$, $C_L = 50\text{ pF}$ $R_L = 200\text{ k}\Omega$ (See figure 3)	All	10	280	ns
		$V_{DD} = 10\text{ V dc}$, $C_L = 50\text{ pF}$ $R_L = 200\text{ k}\Omega$ $T_A = +25^{\circ}\text{C}$, (See figure 3)	All	5	100	ns
Transition times, low to high level	t_{TLH}	$V_{DD} = 5\text{ V dc}$, $C_L = 50\text{ pF}$ $R_L = 200\text{ k}\Omega$ (See figure 3)	All	10	280	ns
		$V_{DD} = 10\text{ V dc}$, $C_L = 50\text{ pF}$ $R_L = 200\text{ k}\Omega$ $T_A = +25^{\circ}\text{C}$, (See figure 3)	All	5	100	ns

1/ Input current of one input node.

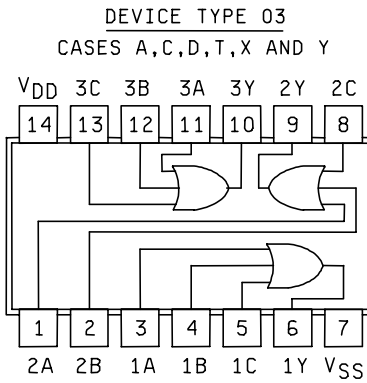
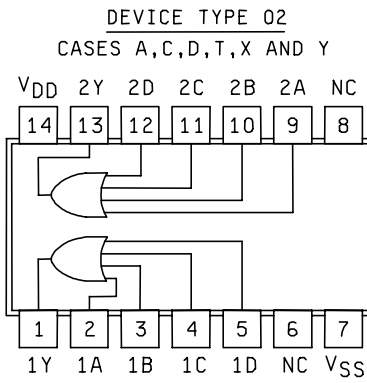
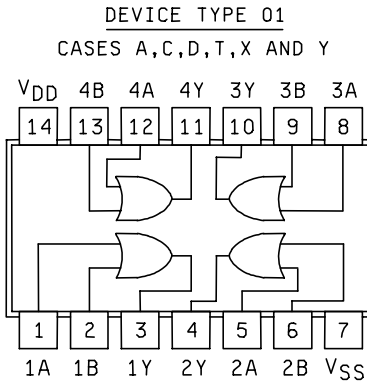


FIGURE 1. Logic diagrams and terminal connections.

Device type 01

Truth table each gate		
Input		Output
A	B	Y
L	L	L
H	L	H
L	H	H
H	H	H

Positive logic $Y = A+B$

Device type 02

Truth table each gate				
Input				Output
A	B	C	D	Y
L	L	L	L	L
H	L	L	L	H
L	H	L	L	H
H	H	L	L	H
L	L	H	L	H
H	L	H	L	H
L	H	H	L	H
H	H	H	L	H
L	L	L	H	H
H	L	L	H	H
L	H	L	H	H
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L	H	H	H	H
H	H	H	H	H

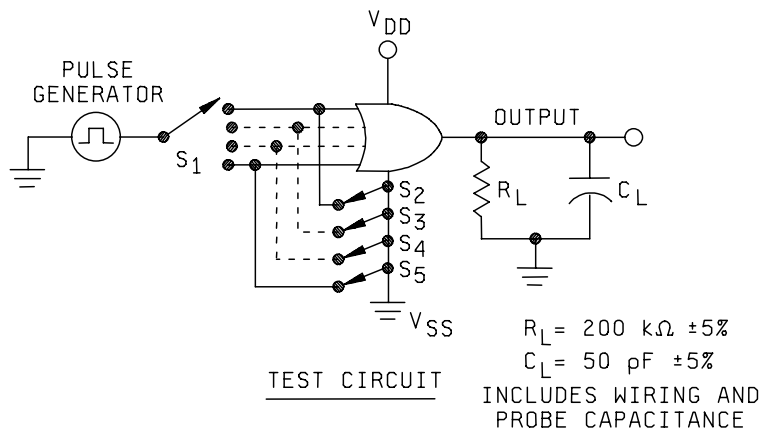
Positive logic $Y = A+B+C+D$

Device type 03

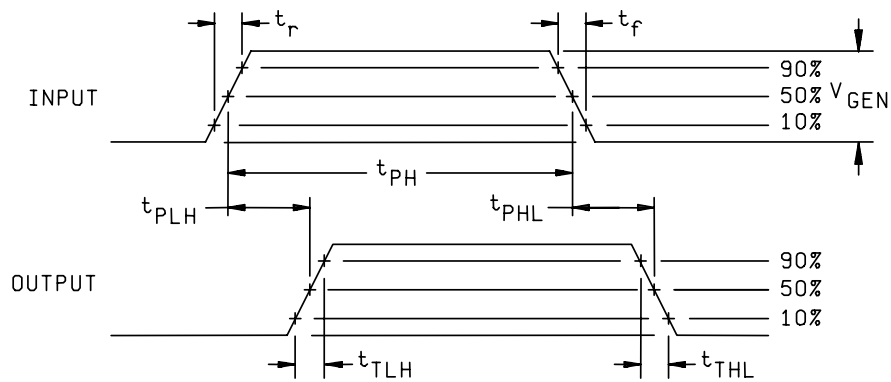
Truth table each gate			
Input			Output
A	B	C	Y
L	L	L	L
H	L	L	H
L	H	L	H
H	H	L	H
L	L	H	H
H	L	H	H
L	H	H	H
H	H	H	H

Positive logic $Y = A+B+C$

FIGURE 2. Truth tables and logic equations.



NOTE: All unused inputs must be tied to V_{DD} .



INPUT PULSE
 $V_{GEN} = V_{DD} \pm 1.0\%$
 $t_{PH} = 1.0 \pm 0.1 \mu s$
 $t_r \text{ AND } t_f \leq 20 \text{ ns}$
 $PRR = 200 \text{ kHz}$

FIGURE 3. Switching time test circuit and waveforms.

4. VERIFICATION

4.1 Sampling and inspection. Sampling and inspection procedures shall be in accordance with MIL-PRF-38535 or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein.

4.2 Screening. Screening shall be in accordance with, MIL-PRF-38535 and shall be conducted on all devices prior to qualification and quality conformance inspection. The following additional criteria shall apply:

- a. The burn-in test duration, test condition, and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-PRF-38535. The burn-in test circuit shall be maintained under document control by the device manufacturer's Technology Review Board (TRB) in accordance with MIL-PRF-38535 and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1015 of MIL-STD-883.
- b. Delete the sequence specified as initial (pre-burn-in) electrical parameters through interim (post-burn-in) electrical parameters of method 5004 and substitute lines 1 through 7 of table II herein.
- c. Burn-in (method 1015 of MIL-STD-883).
 - (1) Unless otherwise specified in the manufacturers QM plan for static tests (test condition A), ambient temperature (T_A) shall be +125°C minimum. Test duration for each static test shall be 24 hours minimum for class S devices and in accordance with table I of method 1015 for class B devices.
 - i. For static burn-in I, all inputs shall be connected to 0.0 V.
 - ii. For static burn-in II, all inputs shall be connected to V_{DD} .
 - iii. Except for V_{DD} and V_{SS} , the terminal shall be connected through resistors whose value is 2 k Ω to 47 k Ω . The actual measured value of the resistor selected shall not exceed $\pm 20\%$ of its branded value due to use, heat or age.
 - iv. Output may be open or connected to $V_{DD}/2$.
 - v. $V_{DD}/2 = V_{DD}/2 \pm 1.0$ V.
 - (2) Unless otherwise specified in the manufacturers QM plan for dynamic test (test condition D), ambient temperature shall be +125°C minimum. Test duration shall be in accordance with table I of method 1015.
 - i. Except for V_{DD} and V_{SS} , the terminals shall be connected through resistors whose value is 2 k Ω to 47 k Ω . The actual measured value of the resistor selected shall not exceed $\pm 20\%$ of its branded value due to use, heat or age.
 - ii. Input signal requirements: Square wave, 50% duty cycle; 25 kHz < PRR < 1 MHz; t_{TLH} and t_{THL} < 1 μ s. Voltage level: Minimum = $V_{SS} - 0.5$ V, +10% V_{DD} ; maximum = $V_{DD} + 0.5$ V, -10% V_{DD} .
 - iii. $V_{DD} = V_{DD}/2 \pm 1.0$ V.
- d. Interim and final electrical test parameters shall be as specified in table II.
- e. For class S devices, post dynamic burn-in, or class B devices, post static burn-in, electrical parameter measurements may, at the manufacturer's option, be performed separately or included in the final electrical parameter requirements.

TABLE II. Electrical test requirements.

Line no.	MIL-PRF-38535 test requirements	Class S device <u>1/</u>			Class B device <u>1/</u>		
		Ref. par.	Table III Subgroups <u>2/</u>	Table IV delta limits <u>3/</u>	Ref. par.	Table III subgroups <u>2/</u>	Table IV delta limits <u>3/</u>
1	Interim electrical parameters		1			1	
2	Static burn-in I (method 1015)	4.2c 4.5.2					
3	Same as line 1		1	Δ			
4	Static burn-in II (method 1015)	4.2c 4.5.2			4.2c 4.5.2	<u>4/</u>	
5	Same as line 1	4.2d	1*	Δ	4.2e	1*	Δ
6	Dynamic burn-in (method 1015)	4.2c 4.5.2					
7	Same as line 1	4.2e	1*	Δ			
8	Final electrical parameters (method 5004)		1*, 2, 3, 9			1*, 2, 3, 9, 10, 11	
9	Group A test requirements (method 5005)	4.4.1	1, 2, 3, 4, 9, 10, 11, 12		4.4.1	1, 2, 3, 4, 9	
10	Group B test when using method 5005 QCI option	4.4.2	1, 2, 3, 9, 10, 11	Δ			
11	Group C end-point electrical parameters (method 5005)				4.4.3	1, 2,3	Δ
12	Group D end-point electrical parameters (method 5005)	4.4.4	1, 2, 3		4.4.4	1, 2, 3	

1/ Blank spaces indicate tests are not applicable.

2/ * indicates PDA applies to subgroup 1 (see 4.2.1).

3/ Δ indicates delta limits shall be required only on table III subgroup 1, where specified, and the delta values shall be computed with reference to the previous interim electrical parameters.

4/ The device manufacturer may at his option either perform delta measurements or within 24 hours after burn-in (or removal of bias) perform the final electrical parameter measurements.

4.2.1 Percent defective allowable (PDA).

- a. The PDA for class S devices shall be 5 percent for static burn-in and 5 percent for dynamic burn-in, based on the exact number of devices submitted to each separate burn-in.
- b. Static burn-in I and II failure shall be cumulative for determining the PDA.
- c. The PDA for class B devices shall be in accordance with MIL-PRF-38535 for static burn-in. Dynamic burn-in is not required.
- d. Those devices whose measured characteristics, after burn-in, exceed the specified delta (Δ) limits or electrical parameter limits specified in table III, subgroup 1, are defective and shall be removed from the lot. The verified failures divided by the total number of devices in the lot initially submitted to burn-in shall be used to determine the percent defective for the lot and the lot shall be accepted or rejected based on the specified PDA.

4.3 Qualification inspection. Qualification inspection shall be in accordance with MIL-PRF-38535.

4.4 Technology Conformance inspection (TCI). Technology conformance inspection shall be in accordance with MIL-PRF-38535 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.5).

4.4.1 Group A inspection. Group A inspection shall be in accordance with table III of MIL-PRF-38535 and as follows:

- a. Tests shall be performed in accordance with table II herein.
- b. Subgroups 5, 6, 7, and 8 shall be omitted.
- c. Subgroup 4 (C_i measurement) shall be measured only for initial qualification and after process or design changes that may affect input capacitance. Capacitance shall be measured between the designated terminal and V_{SS} at a frequency of 1 MHz.
- d. Subgroup 12 shall be added to the group A inspection requirements for the class S devices using a sample size series of 15 (acceptance 0) and consist of the procedure, test conditions, and limits specified in table III.
- e. Subgroups 9 and 11 shall be measured only for initial qualification and after process or design changes which may affect dynamic performance.

4.4.2 Group B inspection. Group B inspection shall be in accordance with table II of MIL-PRF-38535.

4.4.3 Group C inspection. Group C inspection shall be in accordance with table IV of MIL-PRF-38535 and as follows:

- a. End-point electrical parameters shall be as specified in table II herein. Delta limits shall apply only to subgroup 1 of group C inspection and shall consist of tests specified in table IV herein.
- b. The steady-state life test duration, test condition, and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-PRF-38535. The burn-in test circuit shall be maintained under document control by the device manufacturer's Technology Review Board (TRB) in accordance with MIL-PRF-38535 and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1005 of MIL-STD-883.

TABLE III. Group A inspection for device type 01.

Symbol	MIL-STD-833 method	Cases A, C, D, T, X, and Y	Terminal conditions 1/														Measured terminal	Test limits						Unit
			1	2	3	4	5	6	7	8	9	10	11	12	13	14		Subgroup 1 T _A = 25°C		Subgroup 2 T _A = 125°C		Subgroup 3 T _A = -55°C		
			Test No.	1A	1B	1Y	2Y	2A	2B	V _{SS}	3A	3B	3Y	4Y	4A	4B		V _{DD}	Min	Max	Min	Max	Min	
V _{IC} (pos)		1	1 mA	1 mA			1 mA	1 mA							GND	1A	1.5					Vdc		
"		2													"	1B	"					"		
"		3					1 mA								"	2A	"					"		
"		4						1 mA							"	2B	"					"		
"		5							1 mA						"	3A	"					"		
"		6								1 mA					"	3B	"					"		
"		7											1 mA		"	4A	"					"		
"		8												1 mA	"	4B	"					"		
V _{IC} (neg)		9	-1 mA	-1 mA				GND								1A	-6.0					"		
"		10						"								1B	"					"		
"		11					-1 mA	"								2A	"					"		
"		12						"								2B	"					"		
"		13						"	-1 mA							3A	"					"		
"		14						"		-1 mA						3B	"					"		
"		15						"					-1 mA			4A	"					"		
"		16						"						-1 mA		4B	"					"		
I _{SS}	3005	17	18.0V	GND			18.0V	GND	"	18.0V	GND			18.0V	GND	18.0V	V _{SS}		-25		-750		nA	
2/	"	18	GND	18.0V			GND	18.0V	"	GND	18.0V			GND	18.0V	18.0V	V _{SS}		-25		-750		nA	
"	"	19	18.0V	18.0V			18.0V	18.0V	"	18.0V	18.0V			18.0V	18.0V	18.0V	V _{SS}		-25		-750		nA	
V _{OH1}	3006	20	15.0V	GND			GND	GND	"	GND	GND			GND	GND	15.0V	1Y	14.95		14.95		14.95	Vdc	
"	"	21	GND	15.0V			GND	GND	"	"	"			"	"	1Y	"	"	"	"	"	"		
"	"	22	"	GND			15.0V	GND	"	"	"			"	"	2Y	"	"	"	"	"	"		
"	"	23	"	GND			GND	15.0V	"	"	"			"	"	2Y	"	"	"	"	"	"		
"	"	24	GND	GND			GND	GND	GND	15.0V	GND			GND	GND	15.0V	3Y	"				"		
"	"	25	"	"			"	"	"	GND	15.0V			"	"	3Y	"					"		
"	"	26	"	"			"	"	"	"	GND			15.0V	"	4Y	"					"		
"	"	27	"	"			"	"	"	"	GND			GND	15.0V	4Y	"					"		
V _{OL1}	3007	28	"	"			"	"	"	"	"			GND	GND	"	1Y		.05		.05	.05		
"	"	29	"	"			"	"	"	"	"			"	"	2Y		.05		.05	.05	"		
"	"	30	"	"			"	"	"	"	"			"	"	3Y		.05		.05	.05	"		
"	"	31	"	"			"	"	"	"	"			"	"	4Y		.05		.05	.05	"		
V _{IH1}		32	3.5V	1.5V			"	"	"	"	"			"	"	5.0V	1Y	4.5		4.5		4.5		
"		33	1.5V	3.5V			"	"	"	"	"			"	"	"	1Y	"	"	"	"	"		
"		34	GND	GND			3.5V	1.5V	"	"	"			"	"	"	2Y	"	"	"	"	"		
"		35	"	"			1.5V	3.5V	"	"	"			"	"	"	2Y	"	"	"	"	"		
"		36	"	"			GND	GND	"	3.5V	1.5V			"	"	"	3Y	"	"	"	"	"		
"		37	"	"			"	"	"	1.5V	3.5V			"	"	"	3Y	"	"	"	"	"		
"		38	"	"			"	"	"	GND	GND			3.5V	1.5V	"	4Y	"	"	"	"	"		
"		39	"	"			"	"	"	GND	GND			1.5V	3.5V	"	4Y	"	"	"	"	"		
V _{IH2}		40	7.0V	3.0V			GND	GND	GND	GND	GND			GND	GND	10V	1Y	9.0		9.0		9.0		
"		41	3.0V	7.0V			GND	GND	"	"	"			"	"	1Y	"	"	"	"	"	"		
"		42	GND	GND			7.0V	3.0V	"	"	"			"	"	2Y	"	"	"	"	"	"		
"		43	"	"			3.0V	7.0V	"	"	"			"	"	2Y	"	"	"	"	"	"		
"		44	"	"			GND	GND	"	7.0V	3.0V			"	"	3Y	"	"	"	"	"	"		
"		45	"	"			"	"	"	3.0V	7.0V			"	"	3Y	"	"	"	"	"	"		
"		46	"	"			"	"	"	GND	GND			7.0V	3.0V	4Y	"	"	"	"	"	"		
"		47	"	"			"	"	"	GND	GND			3.0V	7.0V	4Y	"	"	"	"	"	"		
V _{IH3}		48	11.0V	4.0V			GND	GND	GND	GND	GND			GND	GND	15V	1Y	13.5		13.5		13.5		
"		49	4.0V	11.0V			GND	GND	"	"	"			"	"	1Y	"	"	"	"	"	"		
"		50	GND	GND			11.0V	4.0V	"	"	"			"	"	2Y	"	"	"	"	"	"		
"		51	"	"			4.0V	11.0V	"	"	"			"	"	2Y	"	"	"	"	"	"		
"		52	"	"			GND	GND	"	11.0V	4.0V			"	"	3Y	"	"	"	"	"	"		
"		53	"	"			"	"	"	4.0V	11.0V			"	"	3Y	"	"	"	"	"	"		
"		54	"	"			"	"	"	GND	GND			11.0V	4.0V	4Y	"	"	"	"	"	"		
"		55	"	"			"	"	"	GND	GND			4.0V	11.0V	4Y	"	"	"	"	"	"		

See footnotes at end of device type 01.

TABLE III. Group A inspection for device type 01 – Continued.

Symbol	MIL-STD-833 method	Cases A, C, D, T, X, and Y	Terminal conditions 1/														Measured terminal	Test limits						Unit
			1	2	3	4	5	6	7	8	9	10	11	12	13	14		Subgroup 1 T _A = 25°C		Subgroup 2 T _A = 125°C		Subgroup 3 T _A = -55°C		
			Test No.	1A	1B	1Y	2Y	2A	2B	V _{SS}	3A	3B	3Y	4Y	4A	4B		V _{DD}	Min	Max	Min	Max	Min	
V _{IL1}		56	1.5V	1.5V			GND	GND	GND	GND	GND			GND	GND	5V	1Y		0.5		0.5		0.5	V dc
"		57	GND	GND			1.5V	1.5V	"	GND	GND			GND	GND	"	2Y		"		"		"	"
"		58	GND	GND			GND	GND	"	1.5V	1.5V			GND	GND	"	3Y		"		"		"	"
"		59	GND	GND			GND	GND	"	GND	GND			1.5V	1.5V	"	4Y		"		"		"	"
V _{IL2}		60	3.0V	3.0V			GND	GND	GND	GND	GND			GND	GND	10V	1Y		1.0		1.0		1.0	"
"		61	GND	GND			3.0V	3.0V	"	GND	GND			GND	GND	"	2Y		"		"		"	"
"		62	GND	GND			GND	GND	"	3.0V	3.0V			GND	GND	"	3Y		"		"		"	"
"		63	GND	GND			GND	GND	"	GND	GND			3.0V	3.0V	"	4Y		"		"		"	"
V _{IL3}		64	4.0V	4.0V			GND	GND	"	GND	GND			GND	GND	15V	1Y		1.5		1.5		1.5	"
"		65	GND	GND			4.0V	4.0V	"	GND	GND			GND	GND	"	2Y		"		"		"	"
"		66	"	"			GND	GND	"	4.0V	4.0V			GND	GND	"	3Y		"		"		"	"
"		67	"	"			GND	GND	"	GND	GND			4.0V	4.0V	"	4Y		"		"		"	"
I _{OL1}		68	"	"	0.4V			"	"	"	"			GND	GND	5V	1Y	0.51		0.36		0.64		mA
"		69	"	"		0.4V		"	"	"	"			GND	GND	"	2Y	"	"	"	"	"	"	"
"		70	"	"				"	"	"	"	0.4V		GND	GND	"	3Y	"	"	"	"	"	"	"
"		71	"	"				"	"	"	"		0.4V	GND	GND	"	4Y	"	"	"	"	"	"	"
I _{OL2}		72	GND	GND	1.5V			GND	GND	GND	GND			GND	GND	15V	1Y	3.4		2.4		4.2		mA
"		73	"	"		1.5V		"	"	"	"			"	"	15V	2Y	"	"	"	"	"	"	"
"		74	"	"				"	"	"	"	1.5V		"	"	15V	3Y	"	"	"	"	"	"	"
"		75	"	"				"	"	"	"		1.5V	"	"	15V	4Y	"	"	"	"	"	"	"
I _{OH1}		76	5.0V	"	4.6V			"	"	"	"			"	"	5.0V	1Y	-0.51		-0.36		-0.64		"
"		77	GND	5.0V	4.6V			"	"	"	"			"	"	"	1Y	"	"	"	"	"	"	"
"		78	"	GND		4.6V		5.0V	"	"	"			"	"	"	2Y	"	"	"	"	"	"	"
"		79	"	"		4.6V		GND	5.0V	"	"			"	"	"	2Y	"	"	"	"	"	"	"
"		80	"	"				"	"	"	"			"	"	"	3Y	"	"	"	"	"	"	"
"		81	"	"				"	"	"	"	5.0V		"	"	"	3Y	"	"	"	"	"	"	"
"		82	"	"				"	"	"	"	GND	5.0V	4.6V	"	"	4Y	"	"	"	"	"	"	"
"		83	"	"				"	"	"	"	GND	GND	GND		"	4Y	"	"	"	"	"	"	"
I _{OH2}		84	15.0V	"	13.5V			"	"	"	"			"	GND	15.0V	1Y	-3.4		-2.4		-4.2		"
"		85	GND	15.0V	13.5V			"	"	"	"			"	"	"	1Y	"	"	"	"	"	"	"
"		86	"	GND		13.5V		15.0V	GND	"	"			"	"	"	2Y	"	"	"	"	"	"	"
"		87	"	"		13.5V		"	"	"	"			"	"	"	2Y	"	"	"	"	"	"	"
"		88	"	"				"	15.0V	"	"			"	"	"	3Y	"	"	"	"	"	"	"
"		89	"	"				"	"	"	"	15.0V	13.5V		"	"	3Y	"	"	"	"	"	"	"
"		90	"	"				"	"	"	"	GND	GND		13.5V	15.0V	4Y	"	"	"	"	"	"	"
"		91	"	"				"	"	"	"	GND	GND		13.5V	GND	4Y	"	"	"	"	"	"	"
I _{IH1}	3010	92	18.0V	18.0V			18.0V	18.0V	"	18.0V	18.0V			18.0V	18.0V	18.0V	All inputs together		800					nA
I _{IH2}	3010	93	18.0V	GND			GND	GND	GND	GND	GND			GND	GND	18.0V	1A		100		100			nA
"	"	94	GND	18.0V			GND	GND	"	"	"			"	"	"	1B		"		"			"
"	"	95	"	GND			18.0V	GND	"	"	"			"	"	"	2A		"		"			"
"	"	96	"	"			"	GND	"	"	"			"	"	"	2B		"		"			"
"	"	97	"	"			"	GND	"	"	"			"	"	"	3A		"		"			"
"	"	98	"	"			"	"	"	"	18.0V			"	"	"	3B		"		"			"
"	"	99	"	"			"	"	"	"	GND	18.0V			"	"	4A		"		"			"
"	"	100	"	"			"	"	"	"	GND	GND			18.0V	18.0V	4B		"		"			"
I _{IL1} 2/	3009	101	"	"			"	"	"	GND	GND			GND	GND	"	All inputs together		-800					"
I _{IL2}	"	102	"	18.0V			18.0V	18.0V	"	18.0V	18.0V			18.0V	18.0V	18.0V	1A		-100		-100			"
"	"	103	"	"			GND	18.0V	"	"	"			"	"	"	1B		"		"			"
"	"	104	"	18.0V			"	GND	"	"	"			"	"	"	2A		"		"			"
"	"	105	"	"			18.0V	GND	"	"	"			"	"	"	2B		"		"			"
"	"	106	"	"			"	"	"	"	"			"	"	"	3A		"		"			"
"	"	107	"	"			"	"	"	"	GND			"	"	"	3B		"		"			"
"	"	108	"	"			"	"	"	"	18.0V	18.0V			"	"	4A		"		"			"
"	"	109	"	"			"	"	"	"	18.0V	18.0V			GND	18.0V	4B		"		"			"

See footnotes at end of device type 01.

TABLE III. Group A inspection for device type 01 – Continued.

Symbol	MIL-STD-833 method	Cases A, C, D, T, X, and Y	Terminal conditions 1/														Measured terminal	Test limits						Unit
			1	2	3	4	5	6	7	8	9	10	11	12	13	14		Subgroup 4 T _A = 25°C		Test limits		Test limits		
			Test No.	1A	1B	1Y	2Y	2A	2B	V _{SS}	3A	3B	3Y	4Y	4A	4B		V _{DD}	Min	Max				
C _i	3012	110 111 112 113 114 115 116 117	4/ 	4/ 	 	 	4/ 	4/ 	GND 	 	 	 	 	 	 	GND 	1A 1B 2A 2B 3A 3B 4A 4B	 	7.5 	 	 	 	 	pF
																		Subgroup 9 T _A = 25°C		Subgroup 10 T _A = 125°C		Subgroup 11 T _A = -55°C		Unit
																		Min	Max	Min	Max	Min	Max	
t _{PHL}	3003 Fig. 3	118 119 120 121 122 123 124 125	IN GND GND GND GND GND GND GND	GND IN GND IN GND IN GND IN	OUT OUT OUT OUT OUT OUT OUT OUT	 	GND GND GND GND GND GND GND GND	GND GND GND GND GND GND GND GND	GND GND GND GND GND GND GND GND	GND GND GND GND GND GND GND GND	 	 	 	GND GND GND GND GND GND GND GND	GND GND GND GND GND GND GND GND	5.0V 	1A to 1Y 1B to 1Y 2A to 2Y 2B to 2Y 3A to 3Y 3B to 3Y 4A to 4Y 4B to 4Y	13 	250 	18 	350 	13 	250 	ns
t _{PLH}	3003 Fig. 3	126 127 128 129 130 131 132 133	IN GND GND GND GND GND GND GND	GND IN GND IN GND IN GND IN	OUT OUT OUT OUT OUT OUT OUT OUT	 	GND GND GND GND GND GND GND GND	GND GND GND GND GND GND GND GND	GND GND GND GND GND GND GND GND	GND GND GND GND GND GND GND GND	 	 	 	GND GND GND GND GND GND GND GND	GND GND GND GND GND GND GND GND	5.0V 	1A to 1Y 1B to 1Y 2A to 2Y 2B to 2Y 3A to 3Y 3B to 3Y 4A to 4Y 4B to 4Y	13 	250 	18 	350 	13 	250 	ns
t _{THL}	3004 Fig. 3	134 135 136 137 138 139 140 141	IN GND GND GND GND GND GND GND	GND IN GND IN GND IN GND IN	OUT OUT OUT OUT OUT OUT OUT OUT	 	GND GND GND GND GND GND GND GND	GND GND GND GND GND GND GND GND	GND GND GND GND GND GND GND GND	GND GND GND GND GND GND GND GND	 	 	 	GND GND GND GND GND GND GND GND	GND GND GND GND GND GND GND GND	 	1Y 1Y 2Y 2Y 3Y 3Y 4Y 4Y	10 	200 	14 	280 	10 	200 	ns
t _{TLH}	3004 Fig. 3	142 143 144 145 146 147 148 149	IN GND GND GND GND GND GND GND	GND IN GND IN GND IN GND IN	OUT OUT OUT OUT OUT OUT OUT OUT	 	 	 	 	 	 	 	 	 	 	 	1Y 1Y 2Y 2Y 3Y 3Y 4Y 4Y	 	 	 	 	 	 	ns

See footnotes at end of device type 01.

TABLE III. Group A inspection for device type 01 – Continued.

Symbol	MIL-STD-833 method	Cases A, C, D, T, X, and Y	Terminal conditions 1/														Measured terminal	Test limits						Units	
			1	2	3	4	5	6	7	8	9	10	11	12	13	14		Subgroup 12 T _A = 25°C							
			Test No.	1A	1B	1Y	2Y	2A	2B	V _{SS}	3A	3B	3Y	4Y	4A	4B		V _{DD}	Min	Max	Min	Min	Max		Min
t _{PHL}	3003 Fig. 3	150 151 152 153 154 155 156 157	IN GND " " " " " "	GND IN GND " " " "	OUT OUT " " " " " "		GND GND IN GND " " " "	GND GND IN GND " " " "	GND " " " " " " "	GND " " " " " " "	GND " " " " " " "			GND " " " " " " "	GND " " " " " " "	10.0 V " " " " " " "	1A to 1Y 1B to 1Y 2A to 2Y 2B to 2Y 3A to 3Y 3B to 3Y 4A to 4Y 4B to 4Y	6 120 " " " " " "	" " " " " " "						ns
t _{PLH}	"	158 159 160 161 162 163 164 165	IN GND " " " " " "	" IN GND " " " " "	OUT OUT " " " " " "		" " IN GND " " " "	" " IN GND " " " "	" " " " " " "	" " " " " " "	" " " " " " "			" " " " " " "	GND " " " " " "	" " " " " " "	1A to 1Y 1B to 1Y 2A to 2Y 2B to 2Y 3A to 3Y 3B to 3Y 4A to 4Y 4B to 4Y	" " " " " " "	" " " " " " "						
t _{THL}	3004 Fig. 3	166 167 168 169 170 171 172 173	IN GND " " " " " "	IN GND " " " " "	OUT OUT " " " " " "		" " IN GND " " " "	" " IN GND " " " "	" " " " " " "	" " " " " " "	" " " " " " "			" " " " " " "	GND " " " " " "	" " " " " " "	1Y 1Y 2Y 2Y 3Y 3Y 4Y 4Y	5 100 " " " " " "	" " " " " " "						
t _{TLH}	"	174 175 176 177 178 179 180 181	IN GND " " " " " "	GND IN GND " " " "	OUT OUT " " " " "		GND GND IN GND " " " "	GND GND IN GND " " " "	GND " " " " " "	GND " " " " " "	GND " " " " " "			GND " " " " " "	GND " " " " " "	10.0V " " " " " " "	1Y 1Y 2Y 2Y 3Y 3Y 4Y 4Y	5 100 " " " " " "	" " " " " " "						ns

1/ Pins not designated may be "HIGH" level logic, "LOW" level logic or open. Exceptions are as follows: V_{IC(pos)} tests, the V_{SS} terminals shall be open; V_{IC(neg)} tests, the V_{DD} terminal shall be open; I_{SS} tests, the output terminals shall be open.

2/ The I_{SS} measurements shall be performed in sequence.

3/ The device manufacturer may, at his option, measure I_{IL} and I_{IH} at 25°C for each individual input or measure all inputs together.

4/ See 4.4.1c.

TABLE III. Group A inspection for device type 02.

Symbol	MIL-STD-833 method	Cases A, C, D, T, X, and Y	Terminal conditions 1/														Measured terminal	Test limits						Units	
			1	2	3	4	5	6	7	8	9	10	11	12	13	14		Subgroup 1 T _A = 25°C		Subgroup 2 T _A = 125°C		Subgroup 3 T _A = -55°C			
			Test No.	1Y	1A	1B	1C	1D	NC	V _{SS}	NC	2A	2B	2C	2D	2Y		V _{DD}	Min	Max	Min	Max	Min		Max
V _{IC} (pos)		1 2 3 4 5 6 7 8		1 mA	1 mA	1 mA	1 mA										GND	1A 1B 1C 1D 2A 2B 2C 2D		1.5 " " " " " "					V _{DC}
V _{IC} (neg)		9 10 11 12 13 14 15 16		-1 mA	-1 mA	-1 mA	-1 mA		GND " " " " " "									1A 1B 1C 1D 2A 2B 2C 2D		-6.0 " " " " " "					
I _{SS} 2/	3005	17 18 19 20 21		18.0V GND GND GND 18.0V	GND 18.0V GND 18.0V 18.0V	GND GND 18.0V GND 18.0V	GND GND GND 18.0V 18.0V		" " " " "		18.0V GND GND GND 18.0V	GND 18.0V GND GND 18.0V	GND GND 18.0V GND 18.0V	GND GND GND 18.0V 18.0V		18.0V " " " "	V _{SS} " " " "		-25 " " " "		-750 " " " "			nA	
V _{OH1}	3006	22 23 24 25 26 27 28 29		15.0V GND " " " " "	GND 15.0V GND 15.0V GND " "	GND GND 15.0V GND 15.0V " "	GND GND GND 15.0V GND " "		GND " " " " "		GND " " 15.0V GND "	GND " " " 15.0V GND "	GND " " " " 15.0V GND "	GND " " " " " 15.0V "		15.0V " " " " " " "	1Y 1Y 1Y 1Y 2Y 2Y 2Y 2Y	14.95 " " " " " "		14.95 " " " " " "		14.95 " " " " " "	V _{DC}		
V _{OL1}	3007	30 31		" "	" "	" "	" "		" "		" "	GND "	GND "	GND "		" "	1Y 2Y		.05 .05		.05 .05		.05 .05	"	
V _{IH1}		32 33 34 35 36 37 38 39		3.5V 1.5V 1.5V 1.5V GND GND GND GND	1.5V 3.5V 1.5V 1.5V GND GND GND GND	1.5V 1.5V 3.5V 1.5V GND GND GND GND	1.5V 1.5V 1.5V 3.5V GND GND GND GND		" " " " " " " "		" " " 3.5V 1.5V 1.5V 1.5V 1.5V	" " " 1.5V 3.5V 1.5V 3.5V 1.5V	" " " " 1.5V 1.5V 1.5V 3.5V		5.0 " " " " " " "	1Y 1Y 1Y 1Y 2Y 2Y 2Y 2Y	4.5 " " " " " " "		4.5 " " " " " " "		4.5 " " " " " " "	"			
V _{IH2}		40 41 42 43 44		7.0V 3.0V 3.0V 3.0V GND	3.0V 7.0V 3.0V 7.0V GND	3.0V 3.0V 7.0V 3.0V GND	3.0V 3.0V 3.0V 7.0V GND		" " " " "		GND " " 7.0V "	GND " " 3.0V "	GND " " 3.0V "	GND " " 3.0V "		10.0V " " " "	1Y 1Y 1Y 2Y	9.0 " " "		9.0 " " "		9.0 " " "	"		
V _{IH2}		45 46 47		GND GND GND	GND GND GND	GND GND GND	GND GND GND		GND " "		3.0V 3.0V 3.0V	7.0V 3.0V 3.0V	3.0V 7.0V 3.0V	3.0V 3.0V 7.0V		10.0V 10.0V 10.0V	2Y 2Y 2Y	9.0V 9.0V 9.0V		9.0V 9.0V 9.0V		9.0V 9.0V 9.0V	V _{DC}		
V _{IH3}		48 49 50 51 52 53 54 55		11.0V 4.0V 4.0V 4.0V GND GND GND GND	4.0V 11.0V 4.0V 4.0V GND GND GND GND	4.0V 4.0V 11.0V 4.0V GND GND GND GND	4.0V 4.0V 11.0V 4.0V GND GND GND GND		" " " " " " " "		GND GND GND GND 11.0V 4.0V 4.0V 4.0V	GND GND GND GND 4.0V 11.0V 4.0V 4.0V	GND GND GND GND 4.0V 4.0V 11.0V 4.0V	GND GND GND GND 4.0V 4.0V 11.0V 11.0V		15.0V " " " " " " "	1Y 1Y 1Y 1Y 2Y 2Y 2Y 2Y	13.5 " " " " " " "		13.5 " " " " " " "		13.5 " " " " " " "	"		
V _{IL1}		56 57		1.5V GND	1.5V GND	1.5V GND	1.5V GND		" "		GND 1.5V	GND 1.5V	GND 1.5V	GND 1.5V		5V 5V	1Y 2Y		0.5 0.5		0.5 0.5		0.5 0.5	"	

See footnotes at end of device type 02.

TABLE III. Group A inspection for device type 02 – Continued.

Symbol	MIL-STD-833 method	Cases A, C, D, T, X, and Y	Terminal conditions 1/														Measured terminal	Test limits						Units
			1	2	3	4	5	6	7	8	9	10	11	12	13	14		Subgroup 1 T _A = 25°C		Subgroup 2 T _A = 125°C		Subgroup 3 T _A = -55°C		
			Test No.	1Y	1A	1B	1C	1D	NC	V _{SS}	NC	2A	2B	2C	2D	2Y		V _{DD}	Min	Max	Min	Max	Min	
V _{IL2}		58		3.0V	3.0V	3.0V	3.0V		GND		GND	GND	GND	GND		10V	1Y		1.0		1.0		1.0	V dc
V _{IL2}		59		GND	GND	GND	GND				3.0V	3.0V	3.0V	3.0V		10V	2Y		1.0		1.0		1.0	"
V _{IL3}		60		4.0V	4.0V	4.0V	4.0V		"		GND	GND	GND	GND		15V	1Y		1.5		1.5		1.5	"
V _{IL3}		61		GND	GND	GND	GND		"		4.0V	4.0V	4.0V	4.0V		15V	2Y		1.5		1.5		1.5	"
I _{OL1}		62		0.4V	"	"	"	"	"		GND	GND	GND	GND		5.0V	1Y	0.51		0.36		0.64		mA
I _{OL1}		63		"	"	"	"	"	"		"	"	"	"	0.4V	5.0V	2Y	0.51		0.36		0.64		"
I _{OL2}		64		1.5V	"	"	"	"	"		"	"	"	"		15V	1Y	3.4		2.4		4.2		"
I _{OL2}		65		"	"	"	"	"	"		"	"	"	"	1.5V	15V	2Y	3.4		2.4		4.2		"
I _{OH1}		66		4.6V	5.0V	"	"	"	"		"	"	"	"		5.0V	1Y	-0.51		-0.36		-0.64		"
I _{OH1}		67		4.6V	GND	5.0V	"	"	"		"	"	"	"		5.0V	1Y	-0.51		-0.36		-0.64		"
I _{OH1}		68		4.6V	GND	GND	5.0V	GND		GND		GND	GND	GND		5.0V	1Y	-0.51		-0.36		-0.64		mA
"		69		4.6V	GND	GND	GND	5.0V		"		GND	GND	"		"	1Y	"		"		"		"
"		70		"	"	"	"	GND		"		5.0V	GND	"		4.6V	2Y	"		"		"		"
"		71		"	"	"	"	GND		"		GND	5.0V	"		4.6V	2Y	"		"		"		"
"		72		"	"	"	"	GND		"		GND	GND	5.0V		4.6V	2Y	"		"		"		"
"		73		"	"	"	"	GND		"		GND	GND	GND	5.0 V	4.6V	2Y	"		"		"		"
I _{OH2}		74		13.5V	15.0V	"	"	"		"		"	"	GND		15.0V	1Y	-3.4		-2.4		-4.2		"
"		75		"	GND	"	"	"		"		"	"	"		"	"	"		"		"		"
"		76		"	"	15.0V	"	"		"		"	"	"		"	"	"		"		"		"
"		77		"	"	GND	"	"		"		"	"	"		"	"	"		"		"		"
"		78		"	"	GND	"	15.0V		"		15.0V	"	"		"	2Y	"		"		"		"
"		79		"	"	"	"	GND		"		GND	"	"		"	"	"		"		"		"
"		80		"	"	"	"	"		"		GND	15.0V	"		"	"	"		"		"		"
"		81		"	"	"	"	"		"		GND	GND	GND	15.0V	"	"	"		"		"		"
I _{IH1} 3/	3010	82		18.0V	18.0V	18.0V	18.0V				18.0V	18.0V	18.0V	18.0V		18.0V	All inputs together		8					nA
I _{IH2}	3010	83		18.0V	GND	GND	GND	GND		"		GND	GND	GND	GND	18.0V	1A		1.0		45			"
"	"	84		GND	18.0V	GND	GND	GND		"		GND	GND	"	"	"	1B		"		"			"
"	"	85		"	GND	18.0V	GND	GND		"		GND	"	"	"	"	1C		"		"			"
"	"	86		"	"	"	18.0V	GND		"		GND	"	"	"	"	1D		"		"			"
"	"	87		"	"	"	18.0V	GND		"		18.0V	"	"	"	"	2A		"		"			"
"	"	88		"	"	"	GND	GND		"		GND	18.0V	"	"	"	2B		"		"			"
"	"	89		"	"	"	GND	GND		"		GND	GND	18.0V	"	"	2C		"		"			"
"	"	90		"	"	"	GND	GND		"		GND	GND	GND	18.0V	"	2D		"		"			"
I _{IL1} 3/	3009	91		GND	GND	GND	GND		GND		GND	GND	GND	GND		18.0V	All inputs together		-8					nA
I _{IL2}	"	92		GND	18.0V	18.0V	18.0V	18.0V		"		18.0V	18.0V	18.0V	18.0V	"	1A		-1.0		-45			"
"	"	93		18.0V	GND	18.0V	18.0V	18.0V		"		"	"	"	"	"	1B		"		"			"
"	"	94		"	18.0V	GND	18.0V	18.0V		"		"	"	"	"	"	1C		"		"			"
"	"	95		"	"	18.0V	GND	18.0V		"		"	"	"	"	"	1D		"		"			"
"	"	96		"	"	"	18.0V	18.0V		"		GND	"	"	"	"	2A		"		"			"
"	"	97		"	"	"	"	"		"		18.0V	GND	"	"	"	2B		"		"			"
"	"	98		"	"	"	"	"		"		18.0V	18.0V	GND	"	"	2C		"		"			"
"	"	99		"	"	"	"	"		"		18.0V	18.0V	18.0V	GND	"	2D		"		"			"
																		Subgroup 4 T _A = 25°C						
																		Min	Max					
C _i	3012	100		4/	4/	4/	4/		GND							GND	1A		7.5					pF
"	"	101		"	"	"	"		"			"	"	"	"	"	1B		"		"			"
"	"	102		"	"	"	"		"			"	"	"	"	"	1C		"		"			"
"	"	103		"	"	"	"	4/	"			"	"	"	"	"	1D		"		"			"
"	"	104		"	"	"	"	"	"		4/	"	"	"	"	"	2A		"		"			"
"	"	105		"	"	"	"	"	"		"	4/	"	"	"	"	2B		"		"			"
"	"	106		"	"	"	"	"	"		"	"	4/	"	"	"	2C		"		"			"
"	"	107		"	"	"	"	"	"		"	"	"	4/	"	"	2D		"		"			"

See footnotes at end of device type 02.

TABLE III. Group A inspection for device type 02 – Continued.

Symbol	MIL-STD-833 method	Cases A, C, D, T, X, and Y	Terminal conditions 1/														Measured terminal	Test limits						Units
			1	2	3	4	5	6	7	8	9	10	11	12	13	14		Subgroup 9 T _A = 25°C		Subgroup 10 T _A = 125°C		Subgroup 11 T _A = -55°C		
			Test No.	1Y	1A	1B	1C	1D	NC	V _{SS}	NC	2A	2B	2C	2D	2Y		V _{DD}	Min	Max	Min	Max	Min	
t _{PHL}	3003 Fig. 3	108 109 110 111 112 113 114 115	OUT OUT OUT OUT	IN GND IN GND	GND IN GND IN	GND GND GND IN	GND GND GND IN		GND		GND GND GND GND	GND	GND GND GND	GND	GND	5.0 V	1A to 1Y 1B to 1Y 1C to 1Y 1D to 1Y 2A to 2Y 2B to 2Y 2C to 2Y 2D to 2Y	13 250	18 350	13 250	ns			
t _{PLH}	3003 Fig. 3	116 117 118 119 120 121 122 123	OUT OUT OUT OUT	IN GND IN GND	IN GND IN GND	GND GND GND IN	GND GND GND IN				IN GND GND GND	IN GND IN GND	GND GND IN GND	GND	OUT OUT OUT OUT		1A to 1Y 1B to 1Y 1C to 1Y 1D to 1Y 2A to 2Y 2B to 2Y 2C to 2Y 2D to 2Y							
t _{THL}	3004 Fig. 3	124 125 126 127 128 129 130 131	OUT OUT OUT OUT	IN GND IN GND	IN GND IN GND	GND GND GND IN	GND GND GND IN				IN GND IN GND	IN GND IN GND	GND GND IN GND	GND	OUT OUT OUT OUT		1Y 1Y 1Y 1Y 2Y 2Y 2Y	10 200	14 280	10 200				
t _{TLH}	3004 Fig. 3	132 133 134 135 136 137 138 139	OUT OUT OUT OUT	IN GND IN GND	IN GND IN GND	GND GND GND IN	GND GND GND IN		GND		GND IN GND GND	GND IN GND GND	GND GND IN GND	GND	OUT OUT OUT OUT	5.0V	1Y 1Y 1Y 1Y 2Y 2Y 2Y	10 200	14 280	13 200	ns			

See footnotes at end of device type 02.

TABLE III. Group A inspection for device type 02 – Continued.

Symbol	MIL-STD-833 method	Cases A, C, D, T, X, and Y	Terminal conditions 1/														Measured terminal	Test limits						Units
			1	2	3	4	5	6	7	8	9	10	11	12	13	14		Subgroup 12 T _A = 25°C						
			Test No.	1Y	1A	1B	1C	1D	NC	V _{SS}	NC	2A	2B	2C	2D	2Y	V _{DD}	Min	Max					
t _{PHL}	3003 Fig. 3	140 141 142 143 144 145 146 147	OUT OUT OUT OUT	IN GND IN IN	GND IN GND IN	GND GND IN GND	GND GND GND IN		GND		GND GND GND GND	GND GND IN GND	GND GND IN GND	GND GND IN IN	OUT OUT OUT OUT	10.0 V	1A to 1Y 1B to 1Y 1C to 1Y 1D to 1Y 2A to 2Y 2B to 2Y 2C to 2Y 2D to 2Y	6 120 " " " " " "	" " " " " " " "					ns
t _{PLH}	"	148 149 150 151 152 153 154 155	OUT OUT OUT OUT	IN GND IN IN	GND IN GND IN	GND GND IN GND	GND GND GND GND		GND		GND GND GND GND	GND GND IN GND	GND GND IN GND	GND GND IN IN	OUT OUT OUT OUT	"	1A to 1Y 1B to 1Y 1C to 1Y 1D to 1Y 2A to 2Y 2B to 2Y 2C to 2Y 2D to 2Y	" " " " " " " "	" " " " " " " "					"
t _{THL}	3004 Fig. 3	156 157 158 159 160 161 162 163	OUT OUT OUT OUT	IN GND IN IN	GND IN GND IN	GND GND IN GND	GND GND GND GND		GND		GND " " " IN IN IN	GND GND GND GND	GND GND IN GND	GND GND IN IN	OUT OUT OUT OUT	10.0V	1Y 1Y 1Y 1Y 2Y 2Y 2Y 2Y	5 " " " " " " "	100 " " " " " " "					ns
t _{TLH}	"	164 165 166 167 168 169 170 171	OUT OUT OUT OUT	IN GND IN IN	GND IN GND IN	GND GND IN GND	GND GND GND GND		GND		GND " " " IN GND GND	GND GND GND GND	GND GND IN GND	GND GND IN IN	OUT OUT OUT OUT	"	1Y 1Y 1Y 1Y 2Y 2Y 2Y 2Y	" " " " " " " "	" " " " " " " "					"

1/ Pins not designated may be "HIGH" level logic, "LOW" level logic or open. Exceptions are as follows: V_{IC(pos)} tests, the V_{SS} terminals shall be open; V_{IC(neg)} tests, the V_{DD} terminal shall be open; I_{SS} tests, the output terminals shall be open.

2/ The I_{SS} measurements shall be performed in sequence.

3/ The device manufacturer may, at his option, measure I_{IL} and I_{IH} at 25°C for each individual input or measure all inputs together.

4/ See 4.4.1c.

TABLE III. Group A inspection for device type 03.

Symbol	MIL-STD-833 method	Cases A, C, D, T, X, and Y	Terminal conditions 1/														Measured terminal	Test limits						Units
			1	2	3	4	5	6	7	8	9	10	11	12	13	14		Subgroup 1 T _A = 25°C		Subgroup 2 T _A = 125°C		Subgroup 3 T _A = -55°C		
			Test No.	2A	2B	1A	1B	1C	1Y	V _{SS}	2C	2Y	3Y	3A	3B	3C		V _{DD}	Min	Max	Min	Max	Min	
V _{IC(pos)}		1 2 3 4 5 6 7 8 9	1 mA	1 mA	1 mA	1 mA	1 mA						1 mA	1 mA	1 mA	GND	1A 1B 1C 2A 2B 2C 3A 3B 3C	1.5 " " " " " " "					Vdc	
V _{IC(neg)}		10 11 12 13 14 15 16 17 18	-1 mA	-1 mA	-1 mA	-1 mA	-1 mA		GND " " " " " "								1A 1B 1C 2A 2B 2C 3A 3B 3C	-6.0 " " " " " " "						
I _{SS} 2/	3005	19 20 21 22	18.0V GND GND 18.0V	GND 18.0V GND 18.0V	18.0V GND GND 18.0V	GND 18.0V GND 18.0V	GND GND 18.0V 18.0V		" " " "	GND GND 18.0V 18.0V			18.0V GND GND 18.0V	GND 18.0V GND 18.0V	GND " V _{SS} "	18.0V " V _{SS} "	V _{SS} V _{SS} V _{SS} V _{SS}	-25 -25 -25 -25		-750 -750 -750 -750			nA	
V _{OH1}	3006	23 24 25 26 27 28 29 30 31	GND GND GND 15.0V GND	GND GND GND 15.0V GND	15.0V GND " " "	GND 15.0V GND 15.0V GND	GND GND 15.0V GND GND		GND " " " " "	GND " " 15.0V GND "			GND " " 15.0V GND "	GND " " 15.0V GND "	GND 15.0V " " 15.0V	15.0V " " " " "	1Y 1Y 1Y 2Y 2Y 3Y 3Y 3Y	14.95 " " " " " " "		14.95 " " " " "	14.95 " " " " "		Vdc	
V _{OL1}	3007	32 33 34	" " "	" " "	" " "	" " "	" " "		" " "	" " "			" " "	" " GND	" " "	1Y 2Y 3Y	" 0.05 0.05 0.05	" 0.05 0.05 0.05	" " "	0.05 0.05 0.05	" " "	0.05 0.05 0.05	Vdc	
V _{IH1}		35 36 37 38 39 40 41 42 43	" " " 3.5V 1.5V 1.5V GND	" " " 1.5V 3.5V 1.5V GND	3.5V 1.5V 1.5V GND " "	1.5V 3.5V 1.5V GND " "	1.5V 1.5V 3.5V GND " "		" " " 1.5V 1.5V GND "	" " " 1.5V 3.5V GND "			" " " 3.5V 1.5V 1.5V	" " " 1.5V 3.5V 3.5V	" 5.0V " " " "	1Y 1Y 1Y 2Y 2Y 3Y 3Y 3Y	4.5 " " " " " "		4.5 " " " "	4.5 " " "		Vdc		
V _{IH2}		44 45 46 47 48 49 50 51 52	" " GND 7.0V 3.0V 3.0V GND	" " GND 7.0V 7.0V 3.0V GND	7.0V 3.0V 3.0V GND " "	3.0V 7.0V 3.0V GND " "	3.0V 7.0V 7.0V GND " "		GND " " GND 3.0V 3.0V 7.0V GND	" " " 3.0V 3.0V 7.0V GND			GND " " 7.0V 3.0V 3.0V	GND " " 3.0V 7.0V 3.0V	GND 10.0V " " " "	1Y 1Y 1Y 2Y 2Y 3Y 3Y 3Y	9.0 " " " " " "		9.0 " " " "	9.0 " " "		Vdc		

See footnotes at end of device type 03.

TABLE III. Group A inspection for device type 03 – Continued.

Symbol	MIL-STD-833 method	Cases A, C, D, T, X, and Y	Terminal conditions 1/														Measured terminal	Test limits						Units
			1	2	3	4	5	6	7	8	9	10	11	12	13	14		Subgroup 1 T _A = 25°C		Subgroup 2 T _A = 125°C		Subgroup 3 T _A = -55°C		
			Test No.	2A	2B	1A	1B	1C	1Y	V _{SS}	2C	2Y	3Y	3A	3B	3C	V _{DD}	Min	Max	Min	Max	Min	Max	
V _{IH3}		53	GND	GND	11.0V	4.0V	4.0V		GND	GND			GND	GND	GND	15.0V	1Y	13.5		13.5		13.5		V dc
"		54	"	"	"	4.0V	11.0V	4.0V	"	"			"	"	"	"	1Y	"	"	"	"	"	"	"
"		55	"	"	"	4.0V	11.0V	4.0V	"	"			"	"	"	"	1Y	"	"	"	"	"	"	"
"		56	11.0V	4.0V	GND	"	GND	"	"	4.0V			"	"	"	"	2Y	"	"	"	"	"	"	"
"		57	4.0V	11.0V	"	"	"	"	"	4.0V			"	"	"	"	2Y	"	"	"	"	"	"	"
"		58	4.0V	4.0V	"	"	"	"	"	11.0V			"	"	"	"	2Y	"	"	"	"	"	"	"
"		59	GND	GND	"	"	"	"	"	GND			11.0V	4.0V	4.0V	"	3Y	"	"	"	"	"	"	"
"		60	GND	GND	"	"	"	"	"	GND			4.0V	11.0V	4.0V	"	3Y	"	"	"	"	"	"	"
"		61	GND	GND	"	"	"	"	"	GND			4.0V	4.0V	11.0V	"	3Y	"	"	"	"	"	"	"
V _{IL1}		62	GND	GND	1.5V	1.5V	1.5V	1.5V	"	GND			GND	GND	GND	5.0V	1Y		0.5		0.5		0.5	"
V _{IL1}		63	1.5V	1.5V	GND	GND	GND	GND	"	1.5V			GND	GND	GND	5.0V	2Y		0.5		0.5		0.5	"
V _{IL1}		64	GND	GND	GND	GND	GND	GND	"	GND			1.5V	1.5V	1.5V	5.0V	3Y		0.5		0.5		0.5	"
V _{IL2}		65	GND	GND	3.0V	3.0V	3.0V	3.0V	"	GND			GND	GND	GND	10.0V	1Y		1.0		1.0		1.0	"
V _{IL2}		66	3.0V	3.0V	GND	GND	GND	GND	"	3.0V			GND	GND	GND	10.0V	2Y		1.0		1.0		1.0	"
V _{IL2}		67	GND	GND	GND	GND	GND	GND	"	GND			3.0V	3.0V	3.0V	10.0V	3Y		1.0		1.0		1.0	"
V _{IL3}		68	GND	GND	4.0V	4.0V	4.0V	4.0V	"	GND			GND	GND	GND	15.0V	1Y		1.5		1.5		1.5	"
V _{IL3}		69	4.0V	4.0V	GND	GND	GND	GND	"	4.0V			GND	GND	GND	15.0V	2Y		1.5		1.5		1.5	"
V _{IL3}		70	GND	GND	GND	GND	GND	GND	"	GND			4.0V	4.0V	4.0V	15.0V	3Y		1.5		1.5		1.5	"
I _{OL1}		71	GND	GND	GND	GND	GND	GND	0.4V	GND	GND			GND	GND	GND	5.0V	1Y	0.51		0.36		0.64	mA
I _{OL1}		72	GND	GND	GND	GND	GND	GND		GND	GND	0.4V		GND	GND	GND	5.0V	2Y	0.51		0.36		0.64	"
I _{OL1}		73	GND	GND	GND	GND	GND	GND		GND	GND		0.4V	GND	GND	GND	5.0V	3Y	0.51		0.36		0.64	"
I _{OL2}		74	GND	GND	GND	GND	GND	GND	1.5V	"	"			GND	GND	GND	15.0V	1Y	3.4		2.4		4.2	mA
I _{OL2}		75	"	"	"	"	"	"		"	"	1.5V		"	"	"	15.0V	2Y	3.4		2.4		4.2	"
I _{OL2}		76	"	"	GND	"	"	"		"	"	1.5V		"	"	"	15.0V	3Y	3.4		2.4		4.2	"
I _{OH1}		77	"	"	5.0V	"	"	4.6V	"	"			"	"	"	5.0V	1Y	-0.51		-0.36		-0.64	"	
"		78	"	"	GND	"	"	4.6V	"	"			"	"	"	"	1Y	"	"	"	"	"	"	"
"		79	"	"	"	"	"	4.6V	"	"			"	"	"	"	1Y	"	"	"	"	"	"	"
"		80	5.0V	"	"	"	"	"	"	"			4.6V	"	"	"	2Y	"	"	"	"	"	"	"
"		81	GND	5.0V	"	"	"	"	"	"			4.6V	"	"	"	2Y	"	"	"	"	"	"	"
"		82	"	"	"	"	"	"	"	"			"	"	"	"	2Y	"	"	"	"	"	"	"
"		83	"	"	"	"	"	"	"	"	5.0V		"	"	"	"	3Y	"	"	"	"	"	"	"
"		84	"	"	"	"	"	"	"	"	4.6V		GND	"	"	"	3Y	"	"	"	"	"	"	"
"		85	"	"	"	"	"	"	"	"	4.6V		"	5.0V	5.0V	"	3Y	"	"	"	"	"	"	"
I _{OH2}		86	"	"	15.0V	"	"	13.5V	"	"			"	"	GND	15.0V	1Y	-3.4		-2.4		-4.2	"	
"		87	"	"	GND	"	"	13.5V	"	"			"	"	"	"	1Y	"	"	"	"	"	"	"
"		88	"	"	"	"	"	"	"	"			"	"	"	"	1Y	"	"	"	"	"	"	"
"		89	15.0V	"	"	"	"	GND	"	"			"	"	"	"	2Y	"	"	"	"	"	"	"
"		90	GND	15.0V	"	"	"	"	"	"	13.5V		"	"	"	"	2Y	"	"	"	"	"	"	"
"		91	"	"	"	"	"	"	"	"	13.5V		"	"	"	"	2Y	"	"	"	"	"	"	"
"		92	"	"	"	"	"	"	"	"	"	15.0V	"	"	"	"	3Y	"	"	"	"	"	"	"
"		93	"	"	"	"	"	"	"	"	GND	"	"	"	"	"	3Y	"	"	"	"	"	"	"
"		94	"	"	"	"	"	"	"	"	GND	"	"	"	15.0V	"	3Y	"	"	"	"	"	"	"
I _{IH1} 3/	3010	95	18.0V	18.0V	18.0V	18.0V	18.0V	18.0V		GND	18.0V			18.0V	18.0V	18.0V	All inputs together		900					nA
I _{IH2}	"	96	GND	GND	18.0V	GND	GND	GND	"	"	GND			GND	GND	GND	1A		100		100			"
"	"	97	GND	GND	GND	18.0V	GND	GND	"	"	"			"	"	"	1B		"		"			"
"	"	98	GND	GND	"	"	"	18.0V	"	"	"			"	"	"	1C		"		"			"
"	"	99	18.0V	GND	"	"	"	GND	"	"	"			"	"	"	2A		"		"			"
"	"	100	GND	18.0V	"	"	"	"	"	"	"			"	"	"	2B		"		"			"
"	"	101	"	"	"	"	"	"	"	"	18.0V			"	"	"	2C		"		"			"
"	"	102	"	"	"	"	"	"	"	"	GND			18.0V	"	"	3A		"		"			"
"	"	103	"	"	"	"	"	"	"	"	GND			GND	18.0V	"	3B		"		"			"
"	"	104	"	"	"	"	"	"	"	"	GND			GND	GND	18.0V	3C		"		"			"
I _{IL1} 3/	3009	105	"	"	"	"	"	"		"	GND			GND	GND	GND	All inputs together		-900					"

See notes at end of device type 03.

TABLE III. Group A inspection for device type 03 – Continued.

Symbol	MIL-STD-833 method	Cases A, C, D, T, X, and Y	Terminal conditions 1/														Measured terminal	Test limits						Units	
			1	2	3	4	5	6	7	8	9	10	11	12	13	14		Subgroup 1 T _A = 25°C		Subgroup 2 T _A = 125°C		Subgroup 3 T _A = -55°C			
			Test No.	2A	2B	1A	1B	1C	1Y	V _{SS}	2C	2Y	3Y	3A	3B	3C		V _{DD}	Min	Max	Min	Max	Min		Max
I _{IL2}	"	106	18.0V	18.0V	GND	18.0V	18.0V		GND	18.0V			18.0V	18.0V	18.0V	18.0V	1A		-100		-100		nA		
"	"	107	18.0V	18.0V	18.0V												1B								
"	"	108	18.0V	18.0V		18.0V											1C								
"	"	109	GND	18.0V			GND	18.0V									2A								
"	"	110	18.0V	GND													2B								
"	"	111	"	18.0V													2C								
"	"	112	"	18.0V													3A								
"	"	113	"	18.0V													3B								
"	"	114	"	18.0V													3C								
																		Subgroup 4 T _A = 25°C							
																		Min	Max						
C _i	3012	115			4/		4/			GND						GND	1A		7.5				pF		
"	"	116															1B								
"	"	117	4/					4/									1C								
"	"	118		4/													2A								
"	"	119															2B								
"	"	120															2C								
"	"	121											4/				3A								
"	"	122												4/			3B								
"	"	123													4/		3C								
																		Subgroup 9 T _A = 25°C		Subgroup 10 T _A = 125°C		Subgroup 11 T _A = -55°C			
																		Min	Max	Min	Max	Min	Max		
t _{PHL}	3003 Fig. 3	124	GND	GND	IN	GND	GND	OUT	GND	GND				GND	GND	GND	5.0V	1A to 1Y	13	250	18	350	13	250	ns
"	"	125	GND	GND	"	IN	IN	OUT	"	"				"	"	"	"	1B to 1Y	"	"	"	"	"	"	
"	"	126	GND	GND	"	GND	IN	OUT	"	"				"	"	"	"	1C to 1Y	"	"	"	"	"	"	
"	"	127	IN	GND	"	"	"	"	"	"				"	"	"	"	2A to 2Y	"	"	"	"	"	"	
"	"	128	GND	IN	"	"	"	"	"	"				"	"	"	"	2B to 2Y	"	"	"	"	"	"	
"	"	129	"	GND	"	"	"	"	"	"	IN	OUT		"	"	"	"	2C to 2Y	"	"	"	"	"	"	
"	"	130	"	"	"	"	"	"	"	"	GND			"	"	"	"	3A to 3Y	"	"	"	"	"	"	
"	"	131	"	"	"	"	"	"	"	"	"			"	"	"	"	3B to 3Y	"	"	"	"	"	"	
"	"	132	"	"	"	"	"	"	"	"	"	OUT	OUT	"	"	IN	"	3C to 3Y	"	"	"	"	"	"	
t _{PLH}	"	133	"	"	IN	"	"	OUT	"	"				"	"	GND	"	1A to 1Y	13	250	18	350	13	250	ns
"	"	134	"	"	GND	IN	"	OUT	"	"				"	"	GND	"	1B to 1Y	"	"	"	"	"	"	
"	"	135	"	"	"	IN	IN	OUT	"	"				"	"	GND	"	1C to 1Y	"	"	"	"	"	"	
t _{PLH}	3003 Fig. 3	136	IN	GND	GND	GND	GND		GND	GND	OUT	OUT		GND	GND	GND	5.0V	2A to 2Y	13	250	18	350	13	250	ns
"	"	137	GND	IN	GND	GND	GND		"	"	OUT	OUT		GND	GND	GND	"	2B to 2Y	"	"	"	"	"	"	
"	"	138	GND	GND	GND	GND	GND		"	"	"	OUT		GND	GND	GND	"	2C to 2Y	"	"	"	"	"	"	
"	"	139	GND	GND	GND	GND	GND		"	"	"	OUT	OUT	IN	GND	GND	"	3A to 3Y	"	"	"	"	"	"	
"	"	140	"	"	"	"	"		"	"	"	"		IN	IN	GND	"	3B to 3Y	"	"	"	"	"	"	
"	"	141	"	"	"	"	"		"	"	"	"	OUT	GND	IN	IN	"	3C to 3Y	"	"	"	"	"	"	
t _{THL}	3004 Fig. 3	142	"	"	IN	"	"	OUT	"	"				"	"	GND	"	1Y	10	200	14	280	10	200	ns
"	"	143	"	"	GND	IN	"	"	"	"				"	"	"	"	1Y	"	"	"	"	"	"	
"	"	144	"	"	"	"	"	"	"	"				"	"	"	"	1Y	"	"	"	"	"	"	
"	"	145	IN	"	"	"	"	"	"	"				"	"	"	"	2Y	"	"	"	"	"	"	
"	"	146	GND	IN	"	"	"	"	"	"	OUT	OUT		"	"	"	"	2Y	"	"	"	"	"	"	
"	"	147	"	GND	"	"	"	"	"	"	"	"		"	"	"	"	2Y	"	"	"	"	"	"	
"	"	148	"	"	"	"	"	"	"	"	IN	OUT		"	"	"	"	3Y	"	"	"	"	"	"	
"	"	149	"	"	"	"	"	"	"	"	"	OUT	OUT	IN	IN	"	"	3Y	"	"	"	"	"	"	
"	"	150	"	"	"	"	"	"	"	"	"	"	OUT	GND	IN	IN	"	3Y	"	"	"	"	"	"	
t _{TLH}	"	151	"	"	IN	GND	IN	OUT	"	"				"	"	"	"	1Y	10	200	14	280	10	200	ns
"	"	152	"	"	"	"	"	"	"	"				"	"	"	"	1Y	"	"	"	"	"	"	
"	"	153	"	"	"	"	"	"	"	"				"	"	"	"	1Y	"	"	"	"	"	"	
"	"	154	IN	GND	"	"	"	"	"	"	OUT	OUT		"	"	"	"	2Y	"	"	"	"	"	"	
"	"	155	"	IN	"	"	"	"	"	"	"	"		"	"	"	"	2Y	"	"	"	"	"	"	
"	"	156	"	GND	"	"	"	"	"	"	IN	OUT		"	"	"	"	2Y	"	"	"	"	"	"	
"	"	157	"	"	"	"	"	"	"	"	"	"	OUT	"	"	"	"	3Y	"	"	"	"	"	"	
"	"	158	"	"	"	"	"	"	"	"	"	OUT	OUT	IN	IN	GND	"	3Y	"	"	"	"	"	"	
"	"	159	"	"	"	"	"	"	"	"	"	"	"	GND	IN	IN	"	3Y	"	"	"	"	"	"	

See footnotes at end of device type 03.

TABLE III. Group A inspection for device type 03 – Continued.

Symbol	MIL-STD-833 method	Cases A, C, D, T, X, and Y	Terminal conditions 1/														Measured terminal	Test limits						Units	
			1	2	3	4	5	6	7	8	9	10	11	12	13	14		Subgroup 12 T _A = 25°C							
			Test No.	2A	2B	1A	1B	1C	1Y	V _{SS}	2C	2Y	3Y	3A	3B	3C		V _{DD}	Min	Max					
t _{PHL}	3003 Fig. 3	160	GND	GND	IN	GND	GND	GND	OUT	GND	GND			GND	GND	GND	10.0V	1A to 1Y	6	120					ns
"	"	161	GND	"	"	IN	IN	IN	OUT	"	"			"	"	"	"	1B to 1Y	"	"					"
"	"	162	GND	"	GND	GND	IN	GND	OUT	"	"			"	"	"	"	1C to 1Y	"	"					"
"	"	163	IN	"	"	"	"	"	"	"	"	OUT		"	"	"	"	2A to 2Y	"	"					"
"	"	164	GND	IN	"	"	"	"	"	"	IN	OUT		"	"	"	"	2B to 2Y	"	"					"
"	"	165	"	GND	"	"	"	"	"	"	"	"		"	"	"	"	2C to 2Y	"	"					"
"	"	166	"	"	"	"	"	"	"	"	GND	"	OUT	IN	"	"	"	3A to 3Y	"	"					"
"	"	167	"	"	"	"	"	"	"	"	"	OUT	OUT	IN	IN	"	"	3B to 3Y	"	"					"
"	"	168	"	"	"	"	"	"	"	"	"	"	OUT	GND	GND	IN	"	3C to 3Y	"	"					"
t _{PLH}	"	169	"	"	IN	"	"	"	OUT	"	"			"	"	GND	"	1A to 1Y	6	120					ns
"	"	170	"	"	"	IN	IN	"	OUT	"	"			"	"	"	"	1B to 1Y	"	"					"
"	"	171	"	"	"	"	"	IN	"	"	"			"	"	"	"	1C to 1Y	"	"					"
"	"	172	IN	"	"	"	"	GND	"	"	"	OUT		"	"	"	"	2A to 2Y	"	"					"
"	"	173	GND	IN	"	"	"	"	"	"	"	"		"	"	"	"	2B to 2Y	"	"					"
"	"	174	"	GND	"	"	"	"	"	"	IN	"	OUT	"	"	"	"	2C to 2Y	"	"					"
"	"	175	"	"	"	"	"	"	"	"	GND	"	"	IN	"	"	"	3A to 3Y	"	"					"
"	"	176	"	"	"	"	"	"	"	"	"	"	OUT	GND	IN	"	"	3B to 3Y	"	"					"
"	"	177	"	"	"	"	"	"	"	"	"	"	"	"	IN	"	"	3C to 3Y	"	"					"
t _{THL}	3004 Fig. 3	178	"	"	IN	"	"	"	OUT	"	"			"	"	GND	"	1Y	5	100					ns
"	"	179	"	"	"	"	"	"	OUT	"	"			"	"	"	"	1Y	"	"					"
"	"	180	"	"	"	IN	IN	IN	"	"	"			"	"	"	"	1Y	"	"					"
"	"	181	IN	"	"	GND	GND	GND	"	"	"	OUT		"	"	"	"	2Y	"	"					"
"	"	182	GND	IN	"	GND	GND	GND	"	"	"	"	"	"	"	"	"	2Y	"	"					"
t _{THL}	3004 Fig. 3	183	GND	GND	GND	GND	GND	"	"	GND	IN	OUT	OUT	GND	GND	GND	10.0V	2Y	5	100					ns
"	"	184	"	"	"	"	"	"	"	"	GND	"	OUT	IN	IN	IN	"	3Y	"	"					"
"	"	185	"	"	"	"	"	"	"	"	"	"	"	GND	GND	GND	"	3Y	"	"					"
"	"	186	"	"	"	"	"	"	"	"	"	"	"	IN	IN	IN	"	3Y	"	"					"
t _{TLH}	3004 Fig. 3	187	"	"	IN	"	"	"	OUT	"	"			"	"	GND	"	1Y	5	100					ns
"	"	188	"	"	"	IN	IN	"	OUT	"	"			"	"	"	"	1Y	"	"					"
"	"	189	"	"	"	"	"	"	"	"	"	OUT		"	"	"	"	1Y	"	"					"
"	"	190	IN	"	"	"	"	IN	"	"	"	"	"	"	"	"	"	2Y	"	"					"
"	"	191	GND	IN	"	"	"	"	"	"	"	"	"	"	"	"	"	2Y	"	"					"
"	"	192	"	GND	"	"	"	"	"	"	IN	OUT		"	"	"	"	2Y	"	"					"
"	"	193	"	"	"	"	"	"	"	"	GND	"	OUT	IN	"	"	"	3Y	"	"					"
"	"	194	"	"	"	"	"	"	"	"	GND	"	"	IN	IN	"	"	3Y	"	"					"
"	"	195	"	"	"	"	"	"	"	"	GND	"	"	GND	GND	IN	"	3Y	"	"					"

1/ Pins not designated may be "HIGH" level logic, "LOW" level logic or open. Exceptions are as follows: V_{IC(pos)} tests, the V_{SS} terminals shall be open; V_{IC(neg)} tests, the V_{DD} terminal shall be open; I_{SS} tests, the output terminals shall be open.

2/ The I_{SS} measurements shall be performed in sequence.

3/ The device manufacturer may, at his option, measure I_{IL} and I_{IH} at 25°C for each individual input or measure all inputs together.

4/ See 4.4.1c

4.4.4 Group D inspection. Group D inspection shall be in accordance with table V of MIL-PRF-38535. End-point electrical parameters shall be as specified in table II herein.

4.4.5 Group E inspection. Group E inspection is required only for parts intended to be marked as radiation hardness assured (see 3.7 herein). RHA levels for device classes B and S shall be as specified in MIL-PRF-38535 and 4.5.4 herein.

4.5 Methods of inspection. Methods of inspection shall be specified and as follows:

4.5.1 Voltage and current. Unless otherwise specified, all voltages given are referenced to the microcircuit V_{SS} terminal. Currents given are conventional current and positive when flowing into the referenced terminal.

4.5.2 Burn-in and life test cool down procedures. When the burn-in and life tests are completed and prior to removal of bias voltages, the devices under test (DUT) shall be cooled to a temperature of $25^{\circ}\text{C} \pm 3^{\circ}\text{C}$; then, electrical parameter end-point measurements shall be performed.

TABLE IV. Delta limits at 25°C .

Parameter 1/	Device types		
	01	02	03
I_{SS}	$\pm 10 \text{ nA}$	$\pm 10 \text{ nA}$	$\pm 10 \text{ nA}$
I_{OL1}	$\pm 15\%$	$\pm 15\%$	$\pm 15\%$
I_{OH1}	$\pm 15\%$	$\pm 15\%$	$\pm 15\%$

1/ Each of the above parameters shall be recorded before and after the required burn-in and life tests to determine delta (Δ).

4.5.3 Quiescent supply current (I_{SS} test). When performing quiescent supply current measurements (I_{SS}), the meter shall be placed so that all currents flow through the meter.

4.5.4 Radiation hardness assurance (RHA) testing. The RHA testing shall be performed in accordance with test procedures and sampling specified in MIL-PRF-38535 and herein.

- Before irradiation, selected samples shall be assembled in qualified packages and pass the governing electrical parameters (group A subgroup 1 at 25°C) and also be subjected to the threshold-voltage test in table VII in order to calculate the delta threshold (ΔV_T) after irradiation.
- The devices shall be subjected to a total radiation dose as specified in MIL-PRF-38535 for the radiation hardness assurance level being tested, and meet the end-point electrical parameters as defined in table V at 25°C , after exposure. The start and completion of the end-point electrical parameter measurements shall not exceed 2 hours following irradiation.
- Threshold-voltage test circuit conditions shall be as specified in table VII and figure 4. In situ and remote testing, the tests shall be performed with the devices biased in accordance with table VI and the bias may be interrupted for up to 1 minute to remove devices to the remote bias fixture.
- After irradiation, the devices shall pass the truth table test as specified in subgroup 7 in table III or if subgroup 7 is not required, then an equivalent truth table test shall be performed.

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TABLE V. Radiation hardened end-point electrical parameters at 25°C.

Parameter	All device types	V _{DD}
V _{TN}	0.3 V min	10 V
V _{TP}	2.8 V max	10 V
ΔV _T	1.4 V	10 V
I _{SS}	100 x max limit	18 V
t _{PLH}	1.35 x max limit	5 V
t _{PHL}	1.35 x max limit	5 V

TABLE VI. Bias during exposure to radiation.

Device type	Pin connections <u>1/</u>		
	V _{DD} = 10 V dc (through a 30 kΩ to 60 kΩ resistor)	V _{SS} = GND	V _{DD} = 10 V dc
01	1, 2, 5, 6, 8, 9, 11, 12	7	14
02	2, 3, 4, 5, 9, 10, 11, 12	7	14
03	1, 2, 3, 4, 5, 8, 11, 12, 13	7	14

1/ Pins not designated are open, or may be tied to 10 V dc through a 47 kΩ resistor.

4.6 Data reporting. When specified in the purchase order or contract, a copy of the following data, as applicable, shall be applied.

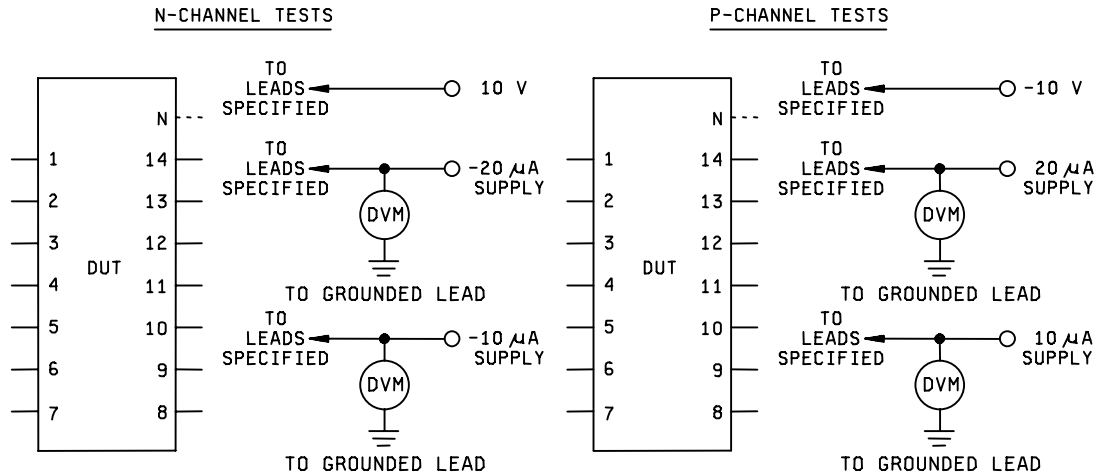
- Attributes data for all screening tests (see 4.2) and variables data for all static burn-in, dynamic burn-in, and steady-state life tests (see 3.6).
- A copy of each radiograph.
- The technology conformance inspection (TCI) data (see 4.4).
- Parameter distribution data on parameters evaluated during burn-in (see 3.6).
- Final electrical parameters data (see 4.2d).
- RHA delta limits.

5. PACKAGING

5.1 Packaging. For acquisition purposes, the packaging requirements shall be as specified in the contract or order (see 6.2). When actual packaging of material is to be performed by DoD or in-house contractor personnel, these personnel need to contact the responsible packaging activity to ascertain requisite packaging requirements. Packaging requirements are maintained by the Inventory Control Point's packaging activity within the Military Department of Defense Agency, or within the military service's system commands. Packaging data retrieval is available from the managing Military Department's or Defense Agency's automated packaging files, CD-ROM products, or by contacting the responsible packaging activity.

6. NOTES

6.1 Intended use. Microcircuits conforming to this specification are intended for original equipment design applications and logistic support of existing equipment.

FIGURE 4. Threshold-voltage test circuit.TABLE VII. Threshold-voltage test circuit conditions.

Device	GND	10 V	V _{TN} measured at		GND	-10 V	V _{TP} measured at	
			-20 μ A supply	-10 μ A supply			20 μ A supply	10 μ A supply
01	1	14		2, 5-9, 12, 13	1	2, 5-9, 12, 13		14
02	2	14		3-5, 7, 9-12	2	3-5, 7, 9-12		14
03	3	14		1, 2, 4, 5, 7, 8, 11, 12, 13	3	1, 2, 4, 5, 7, 8, 11-13		14

6.2 Acquisition requirements. Acquisition documents should specify the following:

- a. Title, number, and date of the specification.
- b. PIN and compliance identifier, if applicable (see 1.2).
- c. Requirements for delivery of one copy of the quality conformance inspection data pertinent to the device inspection lot to be supplied with each shipment by the device manufacturer, if applicable.
- d. Requirements for certificate of compliance, if applicable.
- e. Requirements for notification of change of product or process to contracting activity in addition to notification to the qualifying activity, if applicable.
- f. Requirements for failure analysis (including required test condition of method 5003 of MIL-STD-883), corrective action, and reporting of results, if applicable.
- g. Requirements for product assurance and radiation hardness assurance options.
- h. Requirements for special carriers, lead lengths, or lead forming, if applicable. These requirements should not affect the part number. Unless otherwise specified, these requirements will not apply to direct purchase by or direct shipment to the Government.
- i. Requirements for "JAN" marking.
- j. Packaging requirements. (see 5.1)

6.3 Superseding information. The requirements of MIL-M-38510 have been superseded to take advantage of the available Qualified Manufacturer Listing (QML) system provided by MIL-PRF-38535. Previous references to MIL-M-38510 in this document have been replaced by appropriate references to MIL-PRF-38535. All technical requirements now consist of this specification and MIL-PRF-38535. The MIL-M-38510 specification sheet number and PIN have been retained to avoid adversely impacting existing government logistics systems and contractors parts lists.

6.4 Qualification. With respect to products requiring qualification, awards will be made only for products which are, at the time of award of contract, qualified for inclusion in Qualified Manufacturers List QML-38535 whether or not such products have actually been so listed by that date. The attention of the contractors is called to these requirements, and manufacturers are urged to arrange to have the products that they propose to offer to the Federal Government tested for qualification in order that they may be eligible to be awarded contracts or purchase orders for the products covered by this specification. Information pertaining to qualification of products may be obtained from DSCC-VQ, 3990 E. Broad Street, Columbus, Ohio 43123-1199.

6.5 Abbreviations, symbols, and definitions. The abbreviations, symbols, and definitions used herein are defined in MIL-PRF-38535, MIL-HDBK-1331, and as follows:

C_I	Input terminal-to-GND capacitance.
GND	Ground zero voltage potential.
T_A	Free air temperature.
V_{DD}	Positive supply voltage.
V_{SS}	Negative supply voltage.
I_{SS}	Quiescent supply current.

6.6 Logistic support. Lead materials and finishes (see 3.5) are interchangeable. Unless otherwise specified, microcircuits acquired for Government logistic support will be acquired to device class S for National Aeronautics and Space Administration or class B for Department of Defense (see 1.2.2), lead material and finish A (see 3.5). Longer length leads and lead forming should not affect the part number.

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6.7 Substitutability. The cross-reference information below is presented for the convenience of users. Microcircuits covered by this specification will functionally replace the listed generic-industry type. Generic-industry microcircuit types may not have equivalent operational performance characteristics across military temperature ranges, post irradiation performance or reliability factors equivalent to MIL-M-38510 device types and may have slight physical variations in relation to case size. The presence of this information should not be deemed as permitting substitution of generic-industry types for MIL-M-38510 types or as a waiver of any of the provisions of MIL-PRF-38535.

Military device type	Generic-industry type
01	4071B
02	4072B
03	4075B

6.8 Changes from previous. Marginal notations are not used in this revision to identify changes with respect to the previous issue due to the extensiveness of changes.

CONCLUDING MATERIAL

Custodians:
Army - CR
Navy - EC
Air Force - 11
DLA - CC

Preparing activity:
DLA - CC

(Project 5962-2019)

Review activities:
Army - MI, SM
Navy - AS, CG, MC, SH, TD
Air Force – 03, 19, 99

Note: The activities listed above were interested in this document as of the date of this document. Since organizations and responsibilities can change, you should verify the currency of the information above using ASSIST Online database at www.dodssp.daps.mil.